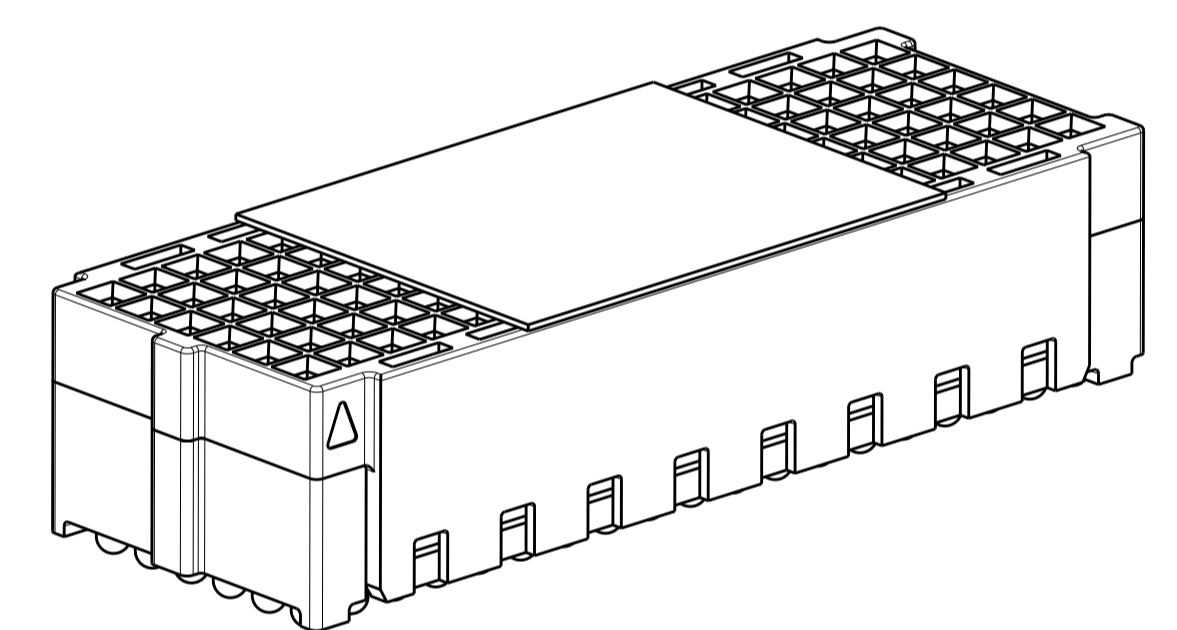
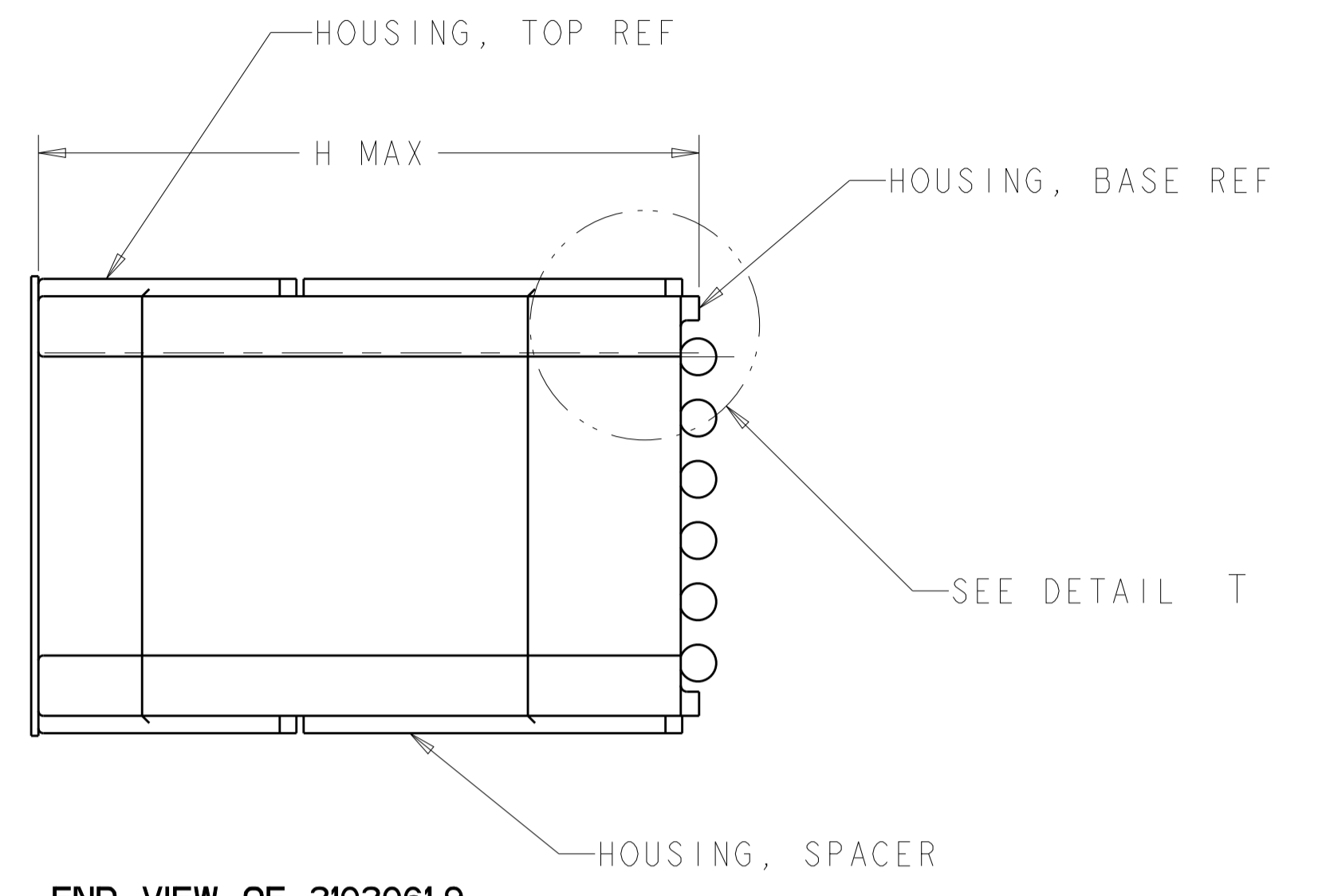
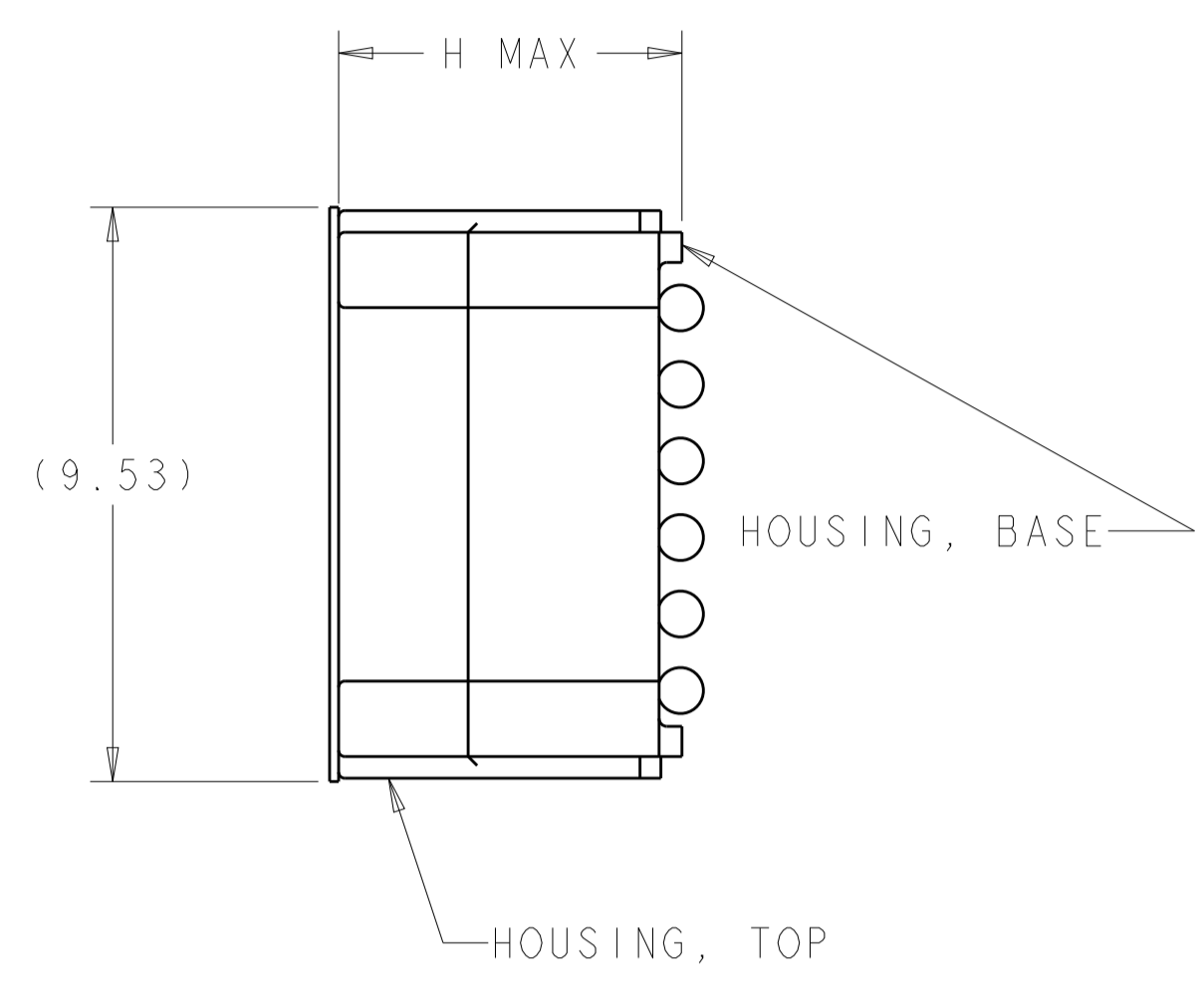
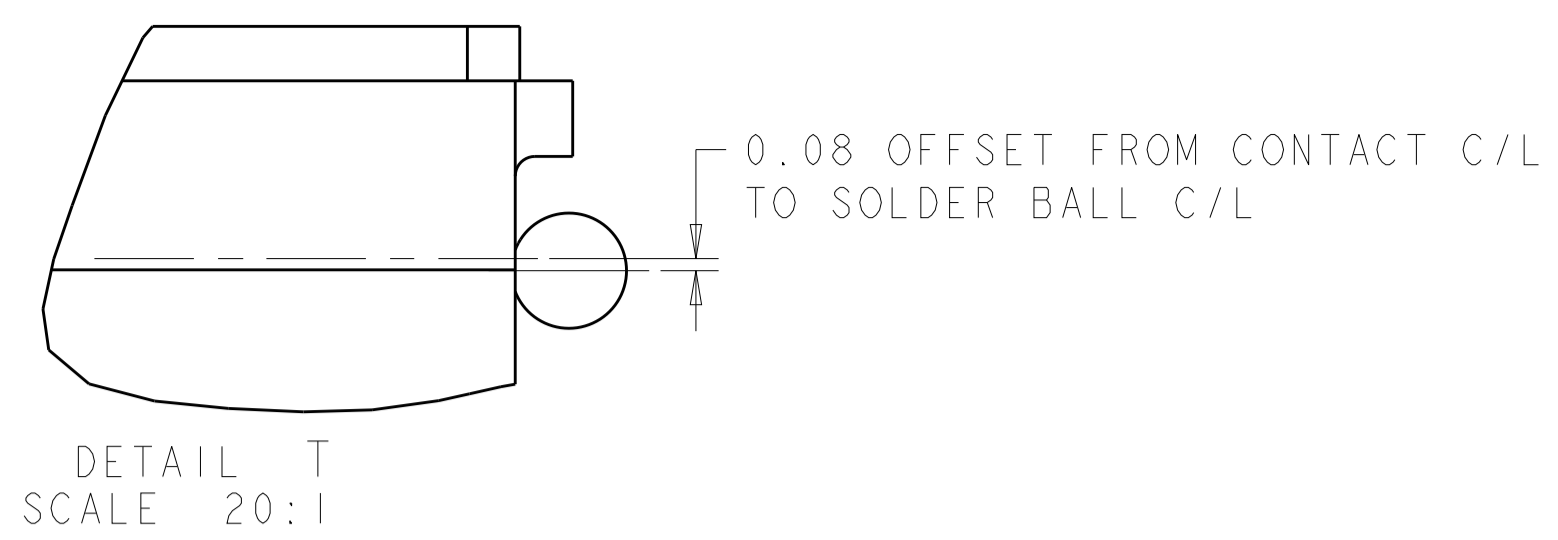
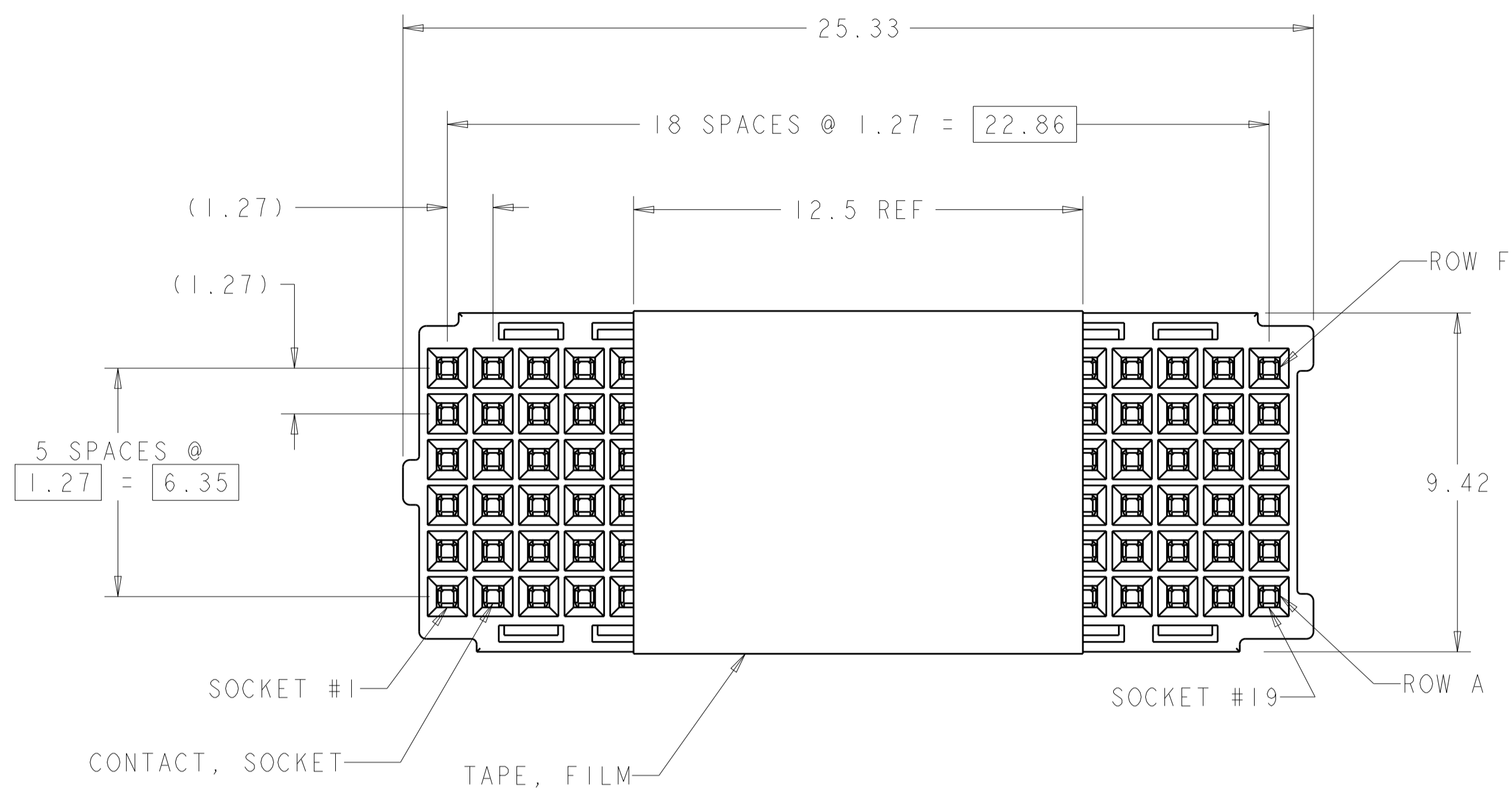
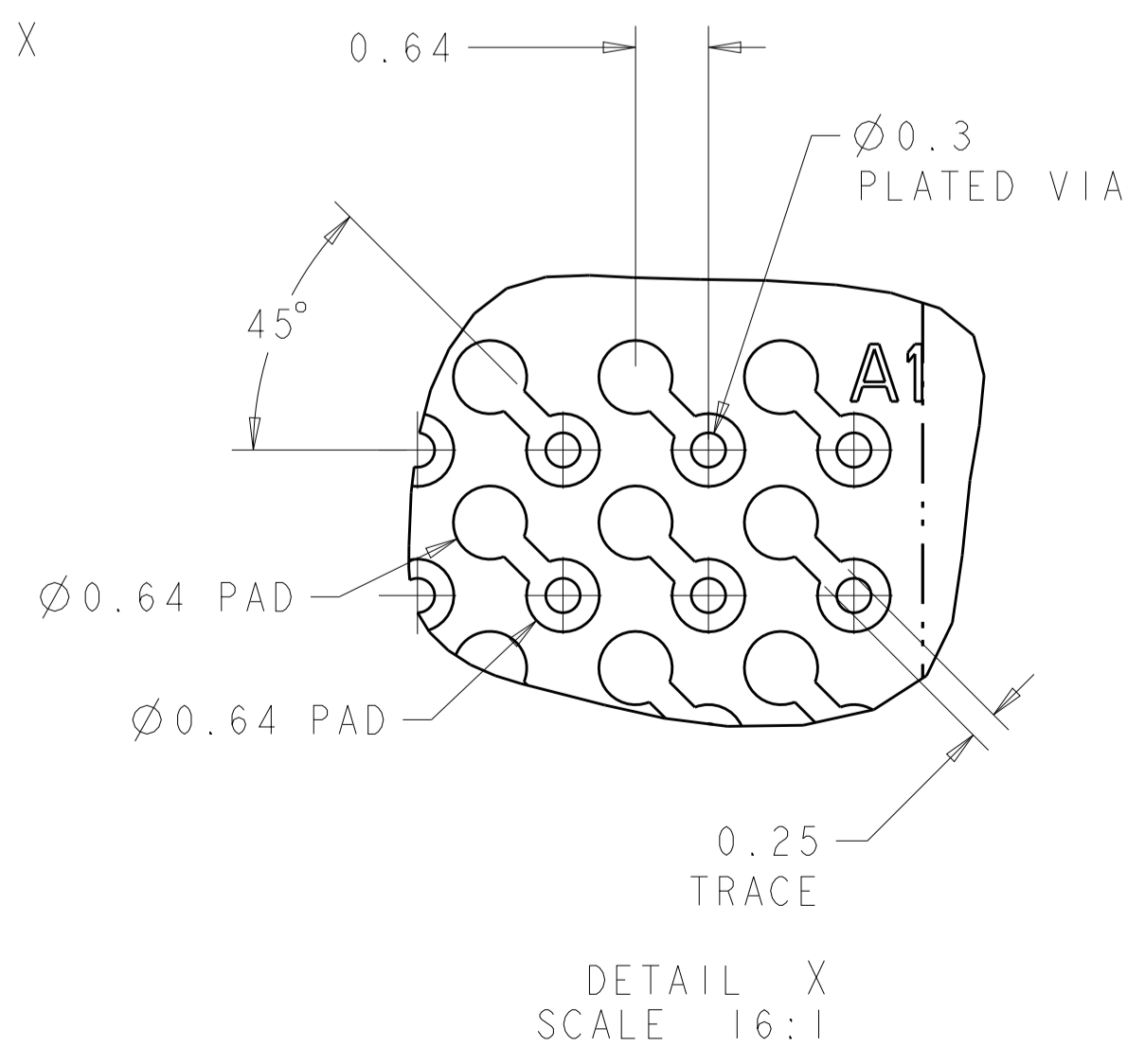
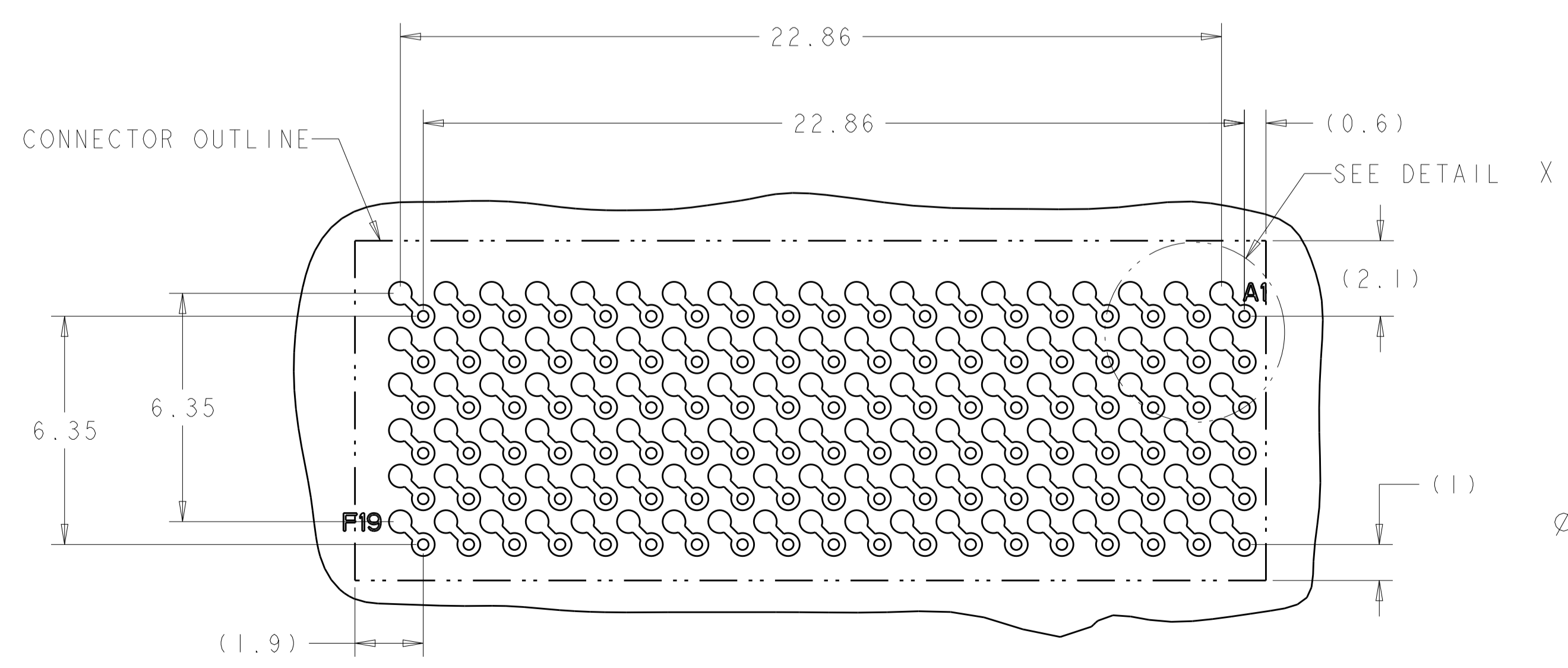
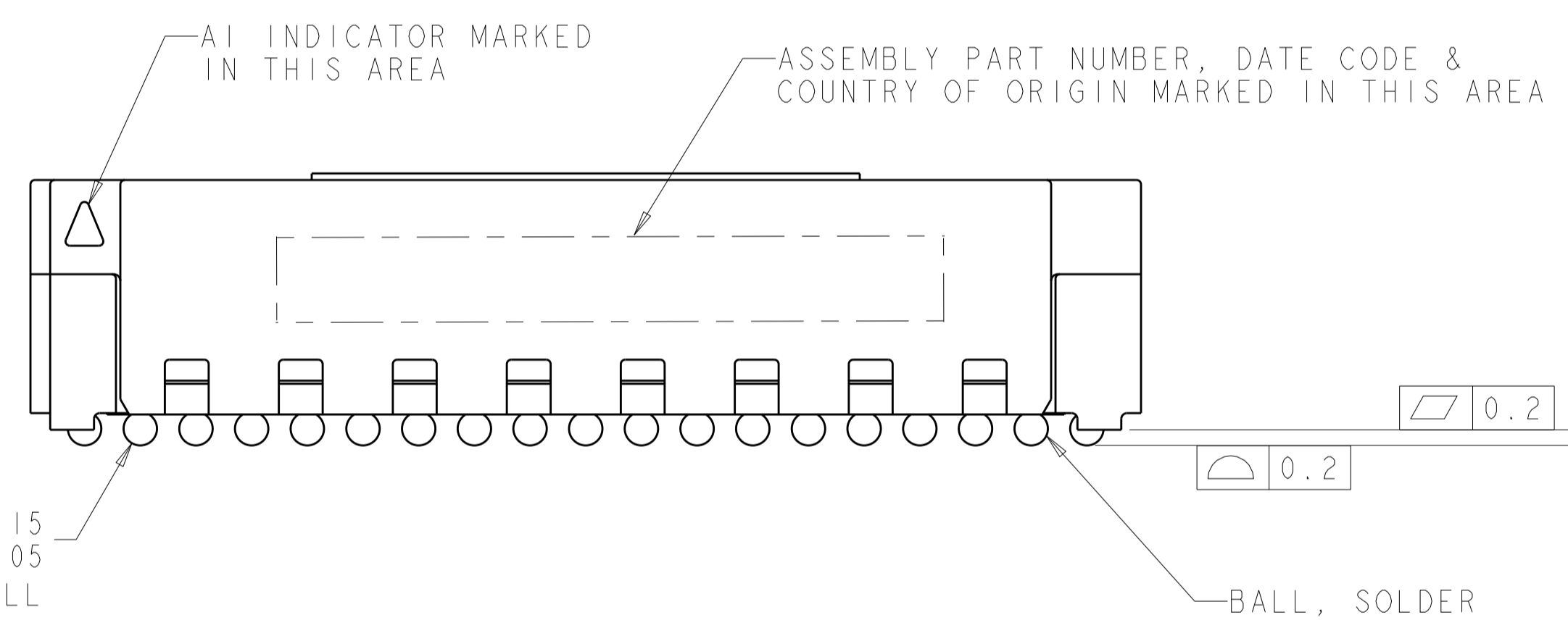


REVISIONS				
P.	LTN	DESCRIPTION	DATE	APPV
L		REV PER ECO 19-012058	8-27-19	CT RL



SCALE 6:1

- ⚠ MATERIAL: HOUSINGS; LCP, COLOR-NATURAL CONTACT; BERYLLIUM COPPER SOLDER BALL; SEE TABLE TAPE, FILM; KAPTON WITH SILICON ADHESIVE
- ⚠ FINISH: CONTACT; GOLD (SEE TABLE) ON MATING AREA OVER NICKEL ON ENTIRE CONTACT.
- 3. PRODUCT IS PACKAGED ON TAPE AND REELED.



MATING PART NUMBER	MATED STACK HEIGHT (mm)	GOLD PLATING THICKNESS	H MAX REF	SOLDER BALL MATERIAL	PART NUMBER
2102060-2	17	1.27 µm	13	LEAD FREE PER SAC405	1-2102061-8
2102060-1	17	1.27 µm	13	TIN LEAD	1-2102061-7
2102060-4	15	0.76 µm	11	LEAD FREE PER SAC405	1-2102061-6
2102060-3	15	0.76 µm	11	TIN LEAD	1-2102061-5
2102060-2	15	1.27 µm	11	LEAD FREE PER SAC405	1-2102061-4
2102060-1	15	1.27 µm	11	TIN LEAD	1-2102061-3
2102060-4	8	0.76 µm	14	LEAD FREE PER SAC405	1-2102061-2
2102060-3	8	0.76 µm	14	TIN LEAD	1-2102061-1
2102060-2	18	1.27 µm	14	LEAD FREE PER SAC405	1-2102061-0
2102060-1	18	1.27 µm	14	TIN LEAD	2102061-9
2102060-4	12	0.76 µm	8	LEAD FREE PER SAC405	2102061-8
2102060-3	12	0.76 µm	8	TIN LEAD	2102061-7
2102060-4	10	0.76 µm	6	LEAD FREE PER SAC405	2102061-6
2102060-3	10	0.76 µm	6	TIN LEAD	2102061-5
2102060-2	12	1.27 µm	8	LEAD FREE PER SAC405	2102061-4
2102060-1	12	1.27 µm	8	TIN LEAD	2102061-3
2102060-2	10	1.27 µm	6	LEAD FREE PER SAC405	2102061-2
2102060-1	10	1.27 µm	6	TIN LEAD	2102061-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

APV: G. DOWNEY 23JUL2009  
CHK: K. DOWHOWER 23JUL2009  
APV: K. DOWHOWER 23JUL2009

**STE** TE Connectivity

NAME: ASSEMBLY, SOCKET, 114 POSITION, MEZALOK STACKING CONNECTOR

SIZE: 114-13279 CAGE CODE: 108-2411 DRAWING NO: A100779 ©=2102061

SCALE: 8:1 SHEET 1 OF 1 REV L